



TECHWISE HUIZHOU(HTT)



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CORE COMPETENCY

- » **High-volume Multi-layer Printed Circuit Boards**

KEY DATA

- » 900000 square feet
- » Maximum Panel Size: 24" × 35"
- » Maximum Board Thickness: 280 mil
- » Aspect Ratio: 12:1
- » Layer Count: 4-32
- » Tracks & Gaps:
 - 3/3mil (External) & 3/3 mil (Internal)
- » Minimum Core Thickness:
 - 2.5 mil (ex copper)
- » Blind and Buried Vias
- » Laser Micro Vias
- » Back Drilling
- » Controlled Impedance and Differential Impedance
- » Multiple Finishes
- » Edge Plating



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CERTIFICATIONS

- ▶ ISO9001
- ▶ UL 796
- ▶ ISO/TS16949
- ▶ ISO14001
- ▶ ROHS
- ▶ ISO9002

PHYSICAL ATTRIBUTES

- ▶ Inner Copper Weight0.25-6oz
- ▶ Outer Copper Weight0.25-6oz
- ▶ SMT Pitch12 mil
- ▶ Core Thickness.....2.5- 96 mil
(ex copper)
- ▶ Board Thickness5-280 mil
- ▶ PTH Aspect Ratio12:1

CAD/CAM

- ▶ Orbotech Workstation
- ▶ Orbotech Laser Plotter

CAPACITY

- ▶ Inner Capacity: 1200000 square feet per month
- ▶ Outer Capacity: 900000 square feet per month

PROCESS CAPABILITY

- ▶ Line / Space
 - Print / Etch Inner Layer.....3/3mil
 - External Layer.....3/3mil
- ▶ Impedance Control.....8%
- ▶ Drilled Hole(min)/Buried Via.....8mil
- ▶ Laser Microvias (min).....4mil
- ▶ Solder Mask Dam..2 mil for Matte Ink
..... 3 mil for Glossy ink
- ▶ Board Thickness Tolerance8%
- ▶ Warp 0.7% (min)
- ▶ Internal Annular RingDHS+10mil
- ▶ External Annular ring.....DHS+10mil
- ▶ Hole to Edge Tolerance±5mil
- ▶ Feature to Edge Tolerance ±5mil

MATERIALS

- ▶ FR4 (Tg 140°C, 150°C and 170°C), Lead Free and Halogen-Free Material
- ▶ CEM-3
- ▶ Low Loss Material - Rogers Getek,
- ▶ Teflon, BT, FR 408 and IS620
Aluminum/steel base



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SURFACE FINISHES

- » HASL
- » OSP& HT OSP
- » Immersion Tin
- » Immersion Gold
- » Deep Tank Hard Gold & Soft Gold
- » Carbon Ink
- » Lead Free HAL
- » Flash Gold
- » Peelable mask.

SOLDER MASK

- » Taiyo, Tamura, Probimer, Greentop, Coates

TEST EQUIPMENT

- » AOI
 - Orbotech/Screen AOI Machine
- » E-Test - Mason E-Tester, Kaima E-Tester
 - ATG E-Tester,
 - ATG and MicroCraft Emma Fly Probe Tester
- » Lab. Testing
 - Cross-section
 - Perfec Test
 - IST and Thermal Cycling
 - CAF



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CORE EQUIPMENT

- ▶ Board Cutting : ACS Auto Sawing Machine
- ▶ Inner D/F : SEMI Auto Exposer Machine
C'Sun & ORC Exposer Machine
- ▶ DES : UCE, AMPOC DES Line
- ▶ BROWN Oxide : UCE , AMPOC Oxide Line
- ▶ Lamination : DATAN & HENGDA Laminator
YAM CHEN Pin Lamination Machine
Mass Lamination with YAMCHEN Machine
- ▶ Multi-line OPE
- ▶ Drilling : Hitachi / Excellon/ Pluritec Machine
Laser Drilling : ESI UV Laser Machine and HITACHI
- ▶ CO2 Laser Drilling Machine
- ▶ Outer D/F : SCHMID AUTO laminator
SEMI AUTO Exposure Machine
- ▶ C'Sun & ORC Exposure Machine
- ▶ SES : AMPOC, UCE SES Line
Solder Mask : SEMI AUTO Printing Machine
- ▶ C'Sun & ORC Exposure Machine
- ▶ HASL : Horizontal HAL Machine
YONGYI HASL Machine
- ▶ Profiling : ORIENTAL Routing Machine
NCV-600 / Schmoll V-cut Machine